

*Amendments In the Claims*

1. (Currently Amended) A method comprising:  
forming a tungsten plug in a dielectric layer;  
forming an electrically conductive interconnect line on the dielectric layer after formation of the tungsten plug, wherein the tungsten plug is electrically connected to the electrically conductive interconnect line;  
contacting the electrically conductive interconnect line with liquid water after formation of the electrically conductive interconnect line;  
contacting the electrically conductive interconnect line with a solution to remove residual polymer after the electrically conductive interconnect line is contacted with the liquid water;  
wherein the electrically conductive interconnect line is contacted with the liquid water for less than 120 minutes.
2. (Currently Amended) The method of claim 1 wherein the liquid water is degasified and deionized.
3. (Currently Amended) The method of claim 1 wherein the liquid water is deionized but not degasified.
4. (Currently Amended) The method of claim 1 wherein the liquid water is degasified but not deionized.
5. (Currently Amended) The method of claim 1 wherein the liquid water is neither degasified nor deionized.
6. (Currently Amended) The method of claim 1 wherein the liquid water has a pH that is at or near neutral.

7. (Currently Amended) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 60 minutes.
8. (Currently Amended) The method of claim 1 wherein the electrically conductive interconnect line is contacted with the liquid water for less than 15 minutes.
9. (Original) The method of claim 1 wherein the electrically conductive interconnect line is formed from a metal stack that includes one or more of titanium, titanium nitride, aluminum, an aluminum copper alloy, and an aluminum silicon copper alloy.
10. - 26. (Canceled).